DB101 THRU DB107

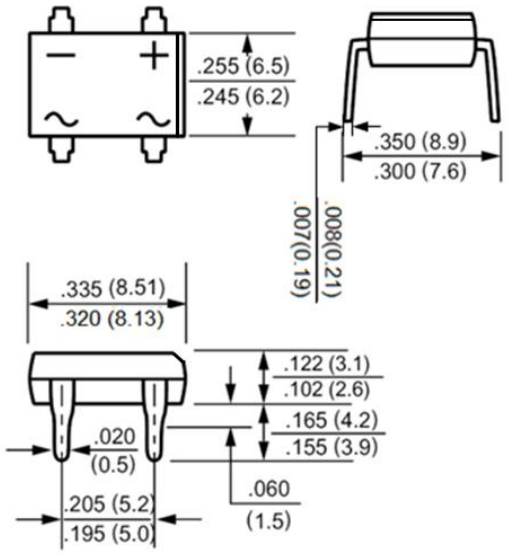
FEATURES

· Glass passivated chip junction
· Low forward voltage drop
· High surge current capability
· Ideal for printed circuit board
· High temperature soldering guaranteed:
260°C for 10 seconds

MECHANICAL DATA

Case: Molded plastic, DB-M
Epoxy: UL 94V-0 rate flame retardant
Terminals: Pure tin plated, lead free, Leads solderable per MIL-STD-202, method 208 guaranteed
Mounting position: as Marking
Weight: 0.34gram

DB-M



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at 25℃ ambient temperature unless otherwise specified.
Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

	Symbols	*DB101*	*DB102*	*DB103*	*DB104*	*DB105*	*DB106*	*DB107*	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	**Volts**
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	**Volts**
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	**Volts**
Maximum Average Forward Rectified Current at T_A=40℃	$I_{(AV)}$	1.0							**Amp**
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	30							**Amp**
Maximum Forward Voltage at 1.0A DC and 25℃	V_F	1.10							**Volts**
Maximum Reverse Current at Rated DC Blocking Voltage at T_A=25℃ T_A=125℃	IR	5.0 500							**uAmp**
Operating and Storage Temperature Range	T_J, Tstg	-55 to +150							℃

FIG.1 FORWARD CURRENT DERATING CURVE

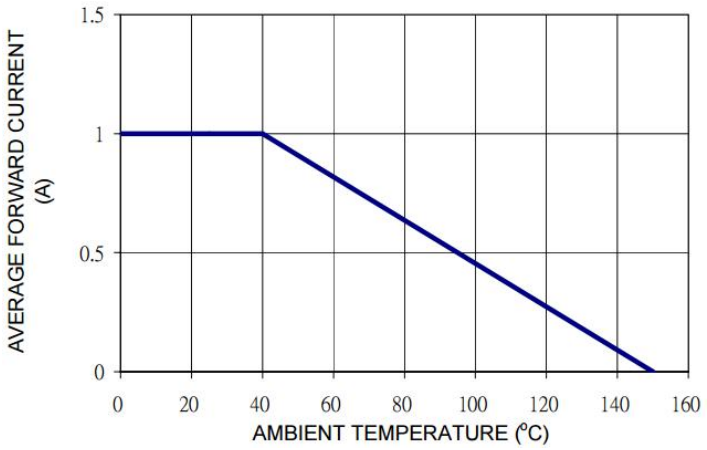


FIG. 2 TYPICAL REVERSE CHARACTERISTICS

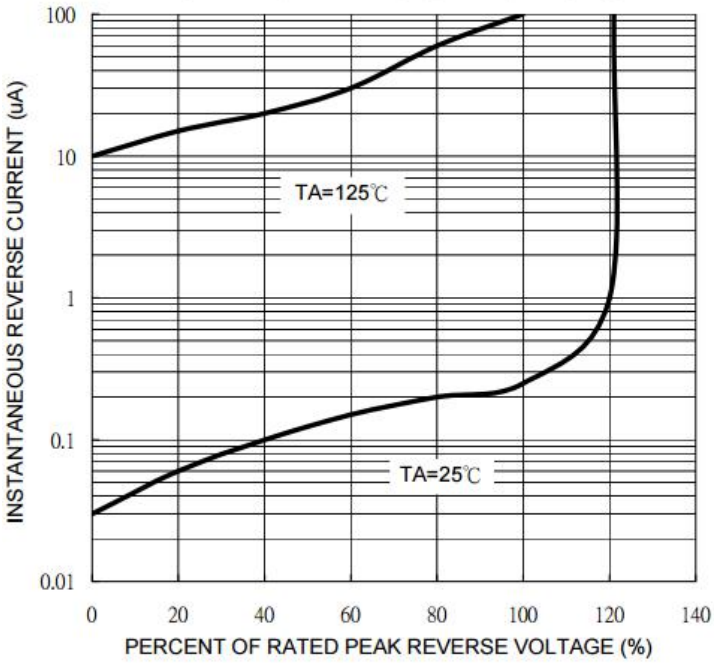


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

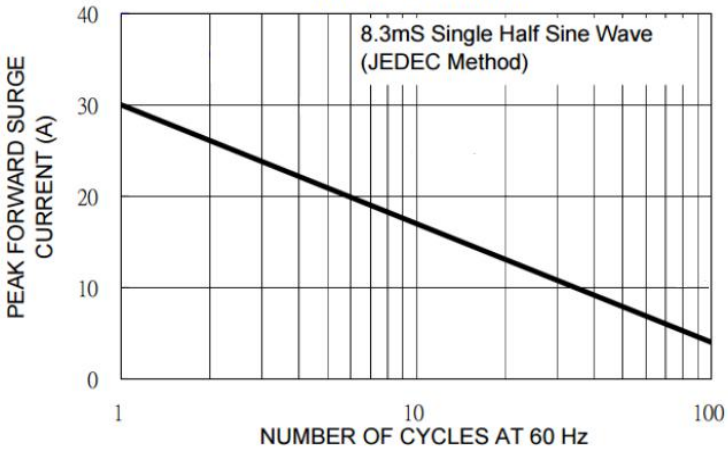


FIG. 5 TYPICAL FORWARD CHARACTERISRICS

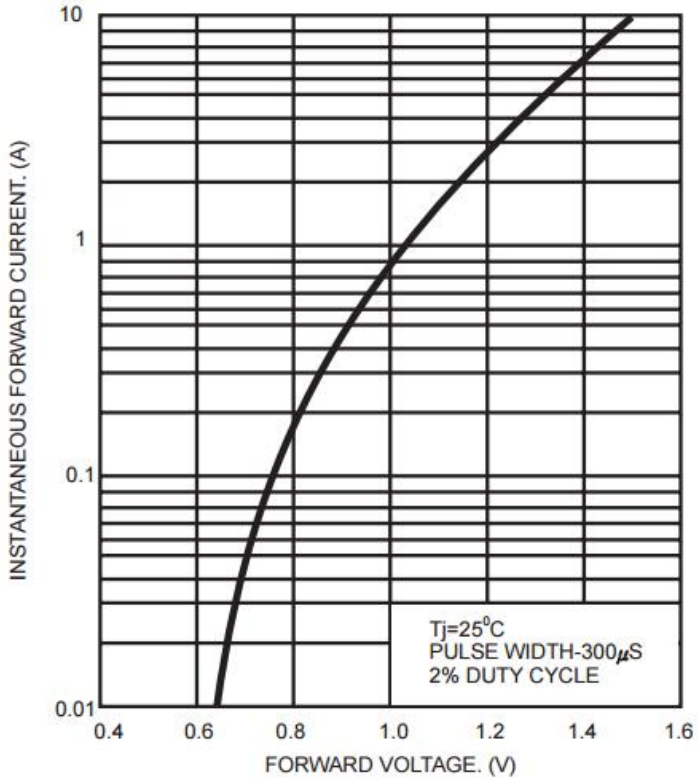


FIG. 4 TYPICAL JUNCTION CAPACITANCE